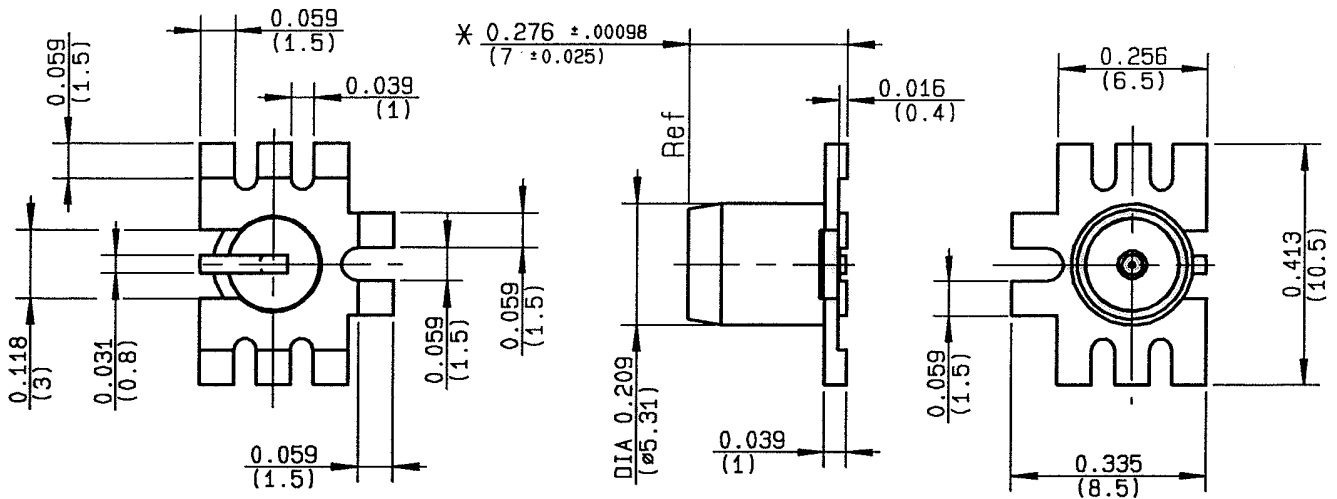
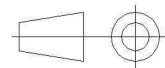


R128.424.848

Series : **BMA COM**

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY	BRASS	TIN 7 OVER COPPER 3
CENTER CONTACT	BRASS	GOLD 0.5 OVER NICKEL 2
OUTER CONTACT	-	-
INSULATOR	PTFE	
GASKET	-	
OTHERS PARTS	-	-
-	-	-
-	-	-

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



MALE STRAIGHT RECEPTACLE FOR PCB**R128.424.848****SMT TYPE****Series : BMA COM****PACKAGING**

Standard	Unit	Other
100	'W' option	Contact us

SPECIFICATION**ELECTRICAL CHARACTERISTICS**

Impedance	50	Ω
Frequency	0-3	GHz
VSWR	1.02 + 0,0500	x F(GHz) Maxi
Insertion loss	0.07	$\sqrt{F}(\text{GHz})$ dB Maxi
RF leakage	NA	- F(GHz)) dB Maxi
Voltage rating	350	Veff Maxi
Dielectric withstanding voltage	1000	Veff mini
Insulation resistance	5000	M Ω mini

ENVIRONMENTAL

Operating temperature	-65/+125	$^{\circ}\text{C}$
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHERS CHARACTERISTICS

Assembly instruction

Others :

-

MECHANICAL CHARACTERISTICS

Center contact retention	
Axial force – Mating end	8 N mini
Axial force – Opposite end	8 N mini
Torque	NA N.cm mini
Recommended torque	
Mating	NA N.cm
Panel nut	NA N.cm
Mating life	500 Cycles mini
Weight	0,9000 g

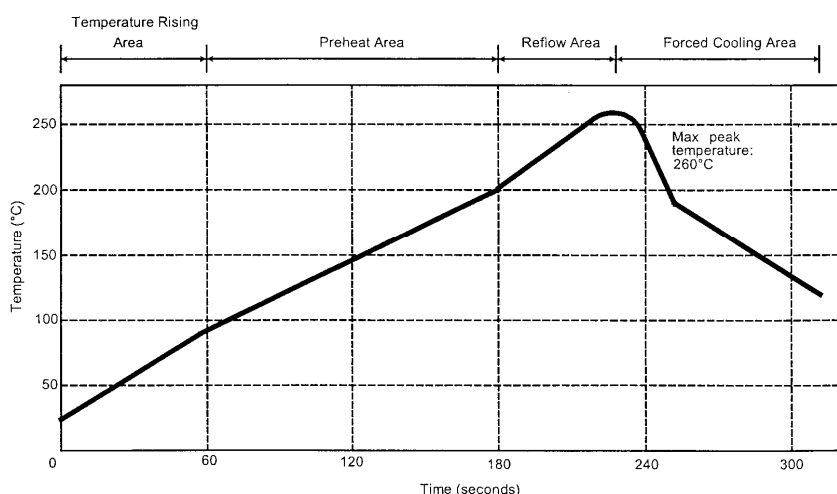
Issue : 0847 C

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MALE STRAIGHT RECEPTACLE FOR PCB**R128.424.848****SMT TYPE**Series : **BMA COM****SOLDER PROCEDURE**

1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
We advise a thickness of 200 microns (7.800 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE

Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0847 C

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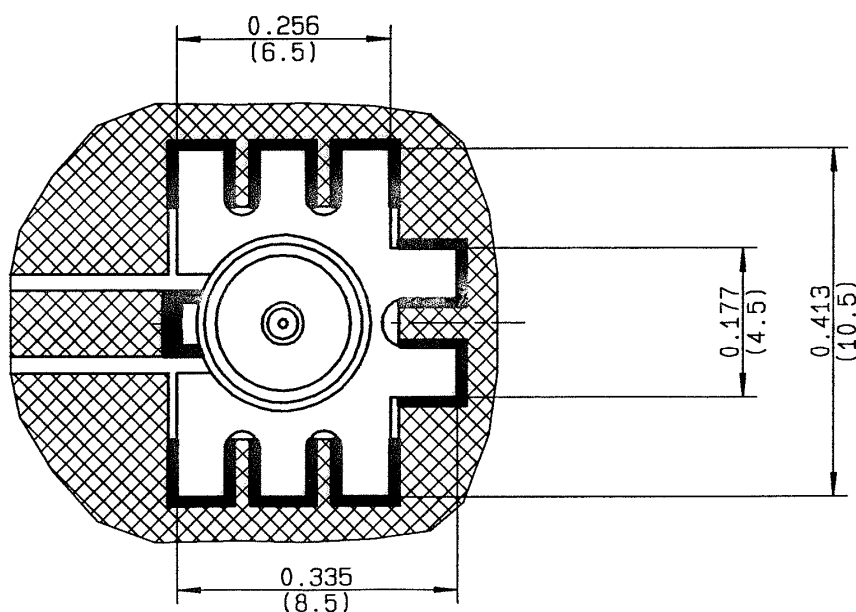
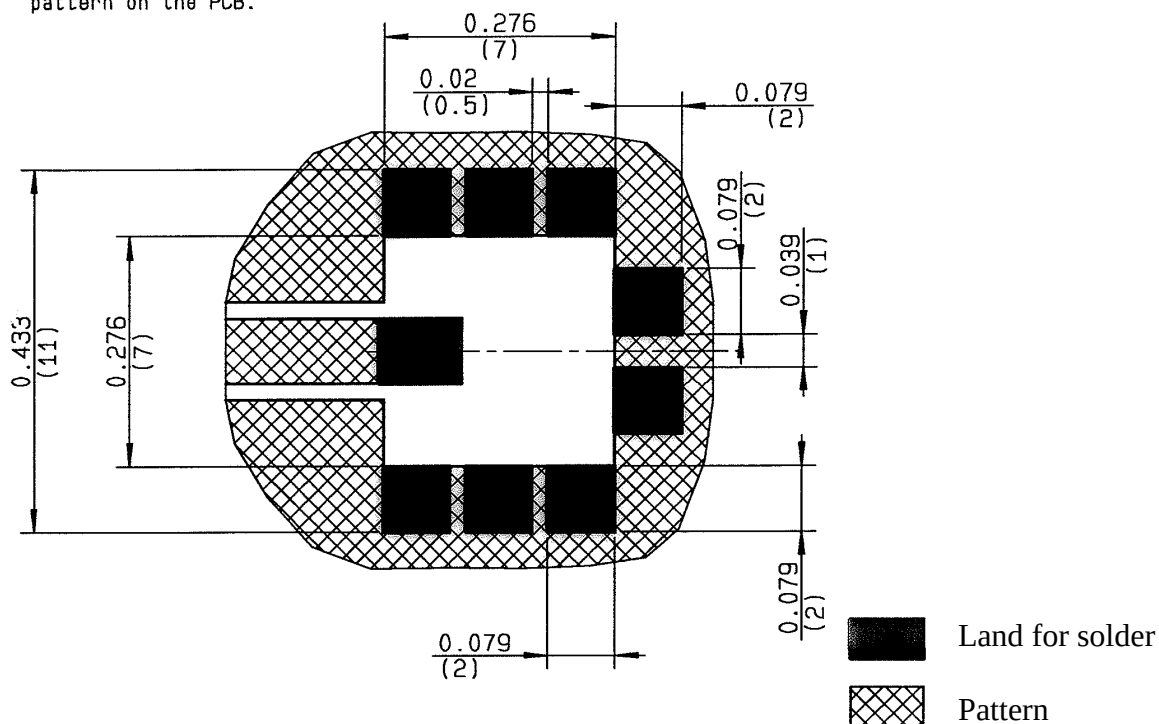


R128.424.848

Series : **BMA COM**

The solder resist should be printed except for the land pattern on the PCB.

BMA SERIES - INFORMATION



In the effort to improve our products, we reserve the right to make changes judged to be necessary.

